BYQ28ED-200PL

Dual ultrafast power diodes

Rev.01 - 23 August 2017 Product data sheet

1. General description

Ultrafast, dual common cathode, epitaxial rectifier diodes in a SOT428 (DPAK) plastic package.

2. Features and benefits

- Fast switching
- Low thermal resistance
- Soft recovery characteristic
- Low forward voltage drop
- Reverse surge capability
- High thermal cycling performance

3. Applications

- Output rectifiers in high-frequency switched-mode power supplies

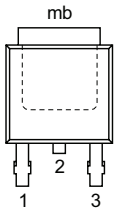
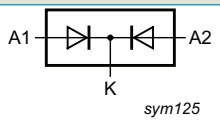
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values				Unit
Absolute maximum rating							
V_{RRM}	repetitive peak reverse voltage		200				V
$I_{O(AV)}$	average output current	δ = 0.5 ; square-wave pulse; $T_{mb} \leq 125$ °C; both diodes conducting; Fig. 1; Fig. 2; Fig. 3	10				A
I_{FRM}	repetitive peak forward current	δ = 0.5 ; t_p = 25 µs; $T_{mb} \leq 130$ °C; square-wave pulse ; per diode	10				A
I_{FSM}	non-repetitive peak forward current	t_p = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; per diode; Fig. 4	50				A
		t_p = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; per diode	55				A
I_{RM}	peak reverse recovery current	t_p = 2 µs; δ = 0.001	0.2				A
I_{RSM}	non-repetitive peak reverse current	t_p = 100 µs	0.2				A
Symbol	**Parameter**	**Conditions**		**Min**	**Typ**	**Max**	**Unit**
Static characteristics							
V_F	forward voltage	I_F = 5 A; T_j = 25 °C; per diode; Fig. 6		-	0.95	1.1	V
		I_F = 5 A; T_j = 150 °C; per diode; Fig. 6		-	0.8	0.895	V
Dynamic characteristics							
t_{rr}	reverse recovery time	I_F = 1 A; V_R = 30 V; dI_F/dt = 100 A/µs; T_j = 25 °C; per diode; Fig. 7		-	15	25	ns

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A	anode	 DPAK (TO252N)	 *sym125*
2	K	cathode		
3	A	anode		
mb	mb	mounting base; connected to cathod		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BYQ28ED-200PL	TO-252	plastic single-ended surface-mounted package (DPAK); 3-leads (one lead cropped)	DPAK

7. Marking

Table 4. Marking codes

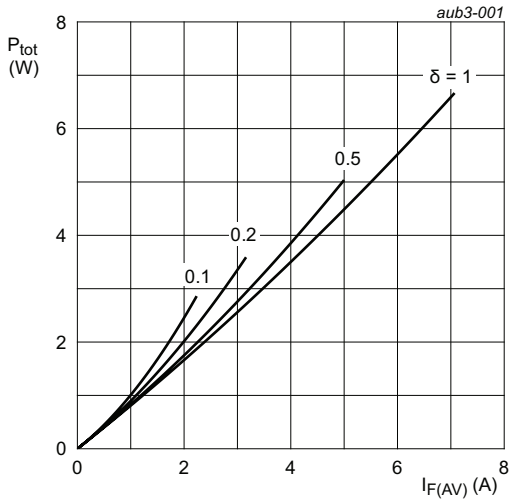
Type number	Marking codes
BYQ28ED-200PL	BYQ28ED-200PL

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

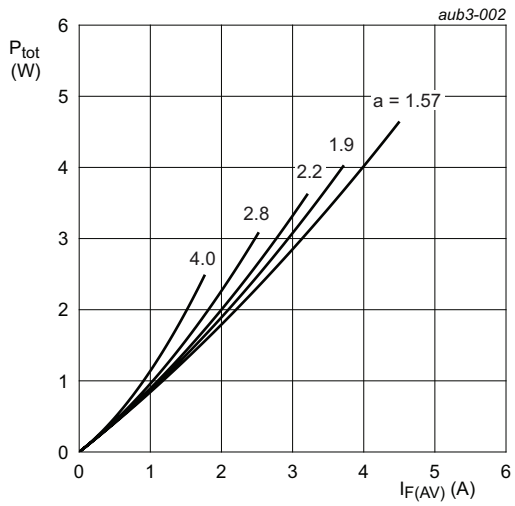
Symbol	Parameter	Conditions	Values	Unit
V_{RRM}	repetitive peak reverse voltage		200	V
V_{RWM}	crest working reverse voltage		200	V
V_R	reverse voltage	DC	200	V
$I_{O(AV)}$	average output current	δ = 0.5 ; square-wave pulse; $T_{mb} \leq 125$ °C; both diodes conducting; Fig. 1; Fig. 2; Fig. 3	10	A
I_{FRM}	repetitive peak forward current	δ = 0.5 ; t_p = 25 µs; $T_{mb} \leq 130$ °C; square-wave pulse ; per diode	10	A
I_{FSM}	non-repetitive peak forward current	t_p = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; per diode; Fig. 4	50	A
		t_p = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; per diode	55	A
I_{RM}	peak reverse recovery current	t_p = 2 µs; δ = 0.001	0.2	A
I_{RSM}	non-repetitive peak reverse current	t_p = 100 µs	0.2	A
T_{stg}	storage temperature		-40 to 150	°C
T_j	junction temperature		150	°C
V_{ESD}	electrostatic discharge voltage	all pin; human body model; C = 250 pF; R = 1.5 kΩ	8	kV



$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$

V_o = 0.787; R_s = 0.0220 Ω

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values; per diode



a = form factor = $I_{F(RMS)} / I_{F(AV)}$

Vo = 0.787 V; Rs = 0.0220 Ω

Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values; per diode

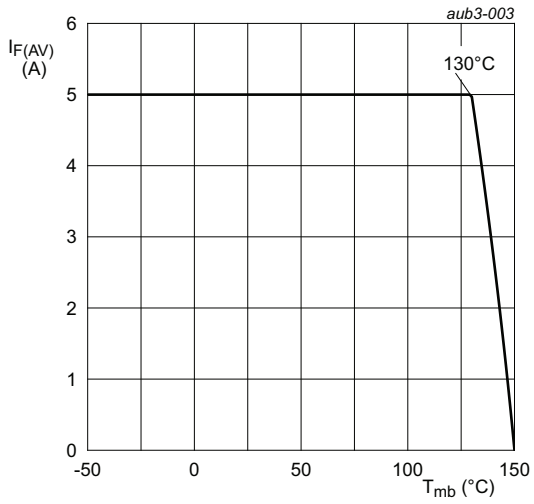


Fig. 3. Forward current as a function of mounting base temperature; maximum values; per diode

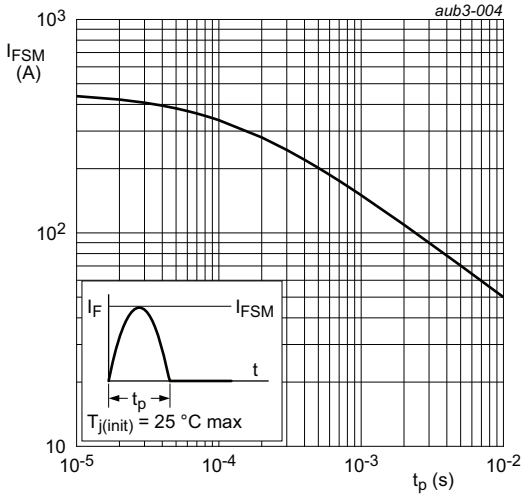


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values; per diode

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	per diode; Fig. 5		-	-	4	K/W
		both diodes conducting; Fig. 5		-	-	2.5	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air		-	60	-	K/W

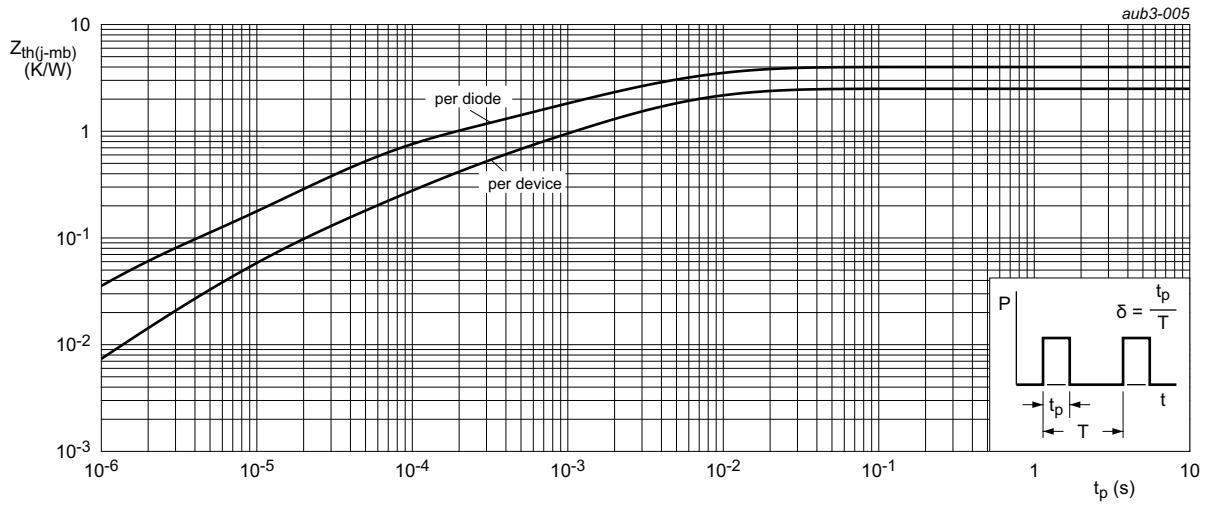
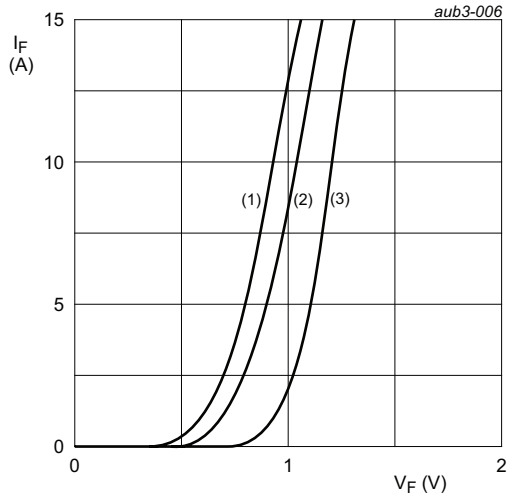


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V_F	forward current	I_F = 5 A; T_j = 25 °C; per diode; Fig. 6		-	0.95	1.1	V
		I_F = 10 A; T_j = 25 °C; per diode; Fig. 6		-	1.1	1.25	V
		I_F = 5 A; T_j = 150 °C; per diode; Fig. 6		-	0.8	0.895	V
I_R	reverse current	V_R = 200 V; T_j = 25 °C; per diode		-	2	10	µA
		V_R = 200 V; T_j = 100 °C; per diode		-	0.1	0.2	mA
Dynamic characteristics							
Q_r	reverse charge	I_F = 2 A; V_R = 30 V; dI_F/dt = 20 A/µs; T_j = 25 °C; per diode; Fig. 7		-	4	9	nC
t_{rr}	reverse recovery time	I_F = 1 A; V_R = 30 V; dI_F/dt = 100 A/µs; T_j = 25 °C; per diode; Fig. 7		-	15	25	ns
I_{RM}	peak reverse recovery current	I_F = 5 A; V_R = 30 V; dI_F/dt = 50 A/µs; T_j = 25 °C; per diode; Fig. 7		-	0.5	0.7	A
V_{FR}	forward recovery voltage	I_F = 1 A; dI_F/dt = 10 A/µs; T_j = 25 °C; per diode		-	1	-	V



V_o = 0.787 V; R_s = 0.0220 Ω
(1) T_j = 150 °C; typical values
(2) T_j = 150 °C; maximum values
(3) T_j = 25 °C; maximum values

Fig. 6. Forward current as a function of forward voltage; per diode

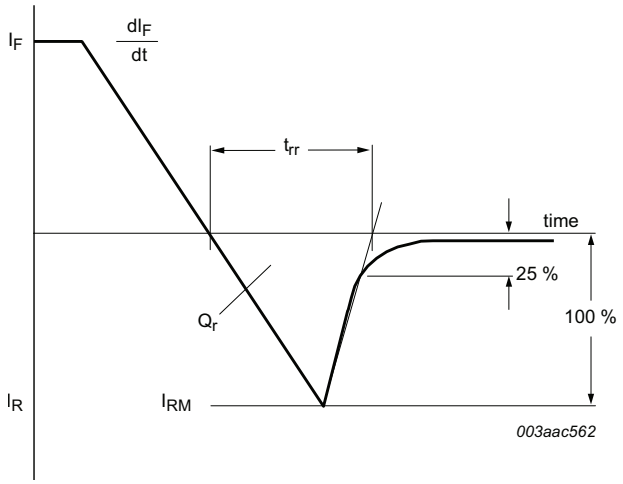
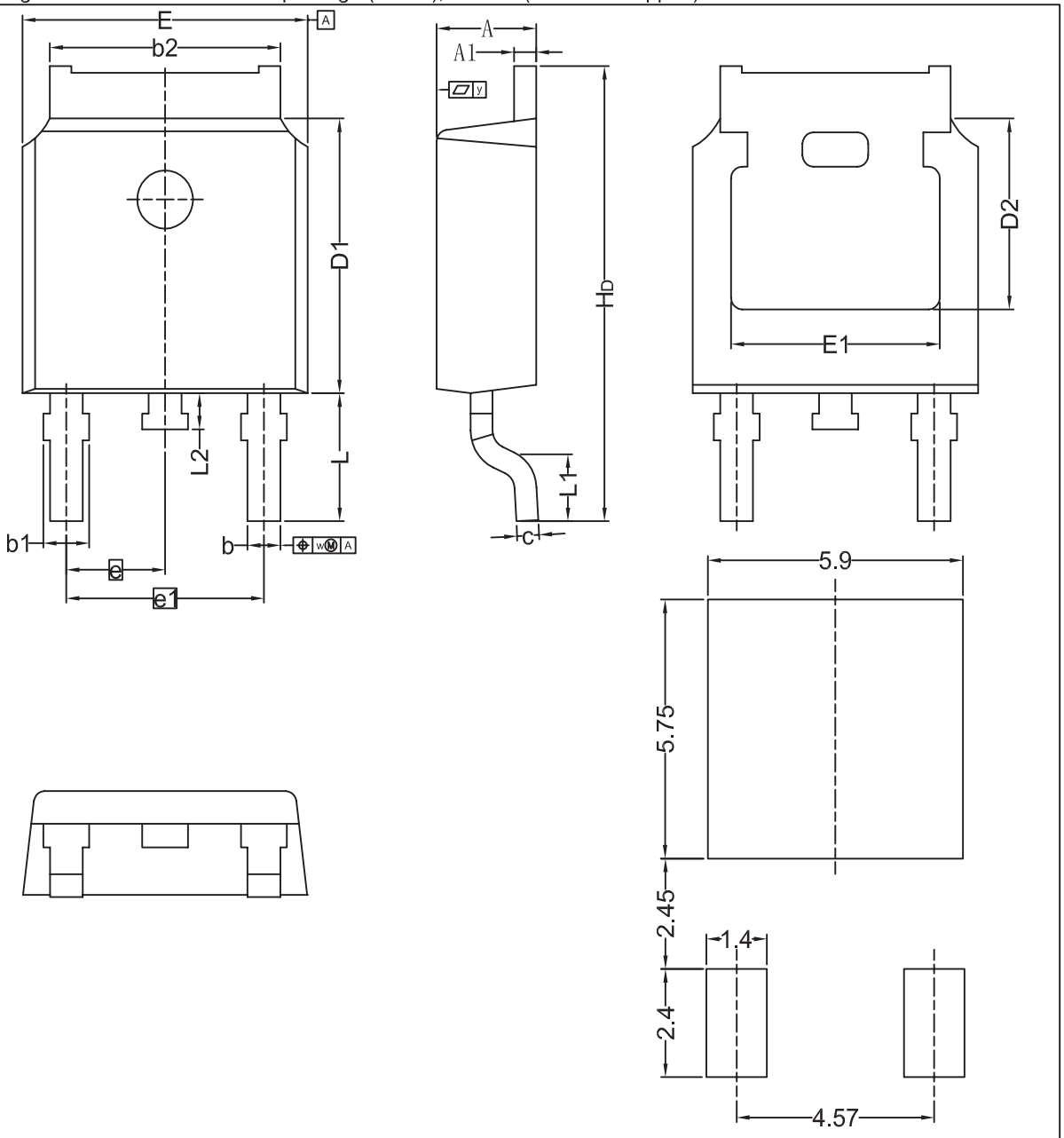


Fig. 7. Reverse recovery definitions; ramp recovery

11. Package outline

Plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped) TO252



Recommended Footprint

Unit	A	A1	b	b1	b2	c	D1	D2	E	E1	e	e1	H_D	L	L1	L2	w	y
min	2.22	0.46	0.71	0.72	5.00	0.20	5.98	4.00	6.47	4.45	2.285	4.57	9.60	2.90 (Ref.)	0.50	0.50	0.20	
mm nom																		
max	2.38	0.93	0.89	1.10	5.46	0.56	6.22	---	6.73	---			10.40		---	0.90		0.20

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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13. Contents

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